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# edaWorkshop15 - Call for Papers

## Submission of Contributions

Download the Call for Papers [here](#) <sup>[1]</sup>.

**The submission deadline is on January 19, 2015. To submit a contribution click [here](#) <sup>[2]</sup>.**

In addition to the presentation of EDA research projects and their results, the edaWorkshop aims at the publication of industrially-relevant R&D results covering topics listed [below](#).

Expected are submissions to the following categories:

1. Scientific contributions from research and industry which present new EDA research and development results
2. Presentations of EDA topics of a visionary or survey character, with scientific or practical impact
3. Contributions to the application relevance of and the economical impact on technical challenges or solutions
4. Reports on experiences or on the dissemination of results from industrial practice
5. Demonstrations of research and development results, in particular those from ICT2020 or CATRENE projects
6. Presentations or sessions on R&D projects demonstrating the applications of microelectronics.

Starting this year, also submissions are encouraged which address the increasing need to consider application aspects during the design process, in particular bridging the gap in the value chain between applications and chip design.

The [program committee](#) consisting of leading EDA experts (named below) from industry and research, will review the contributions by category in order to devise a program of presentations, posters and demonstrations. Accepted contributions will be published in the edaWorkshop proceedings, which will appear in the VDE-Verlag with an ISBN. The proceedings will not distinguish between poster, presentation and demonstration contributions – all contributions are equally important to our common goal.

Conference language will be English.

## Key Dates

**Submission deadline: January 19, 2015**

**Submission of papers, go [here](#) <sup>[2]</sup> for submission**

**February 16, 2015**

**Notification of acceptance**

**March 30, 2015**

**Submission of camera-ready papers**

**May 19 - 21, 2015**

**edaWorkshop in Dresden**

## Modalities

Scientists and users are invited to submit contributions in due time without author and company names on five to six pages, in German or English, preferably in English, at [edaworkshop/upload](#) <sup>[2]</sup>.

Guidelines for authors as well as the templates (Word and LaTeX) can be found here:

- [Templates and guidelines for LaTeX](#) <sup>[3]</sup> (includes German and English)
- [Templates and guidelines for Word](#) <sup>[4]</sup> (includes German and English)

If you urgently need an English version, please get in [contact](#) with us. The Call for Papers as a pdf for download can be found [here](#) <sup>[1]</sup>. Conference language will be English. The duration of oral presentations will be about 20 minutes.

# edaWorkshop15 Topics

Submissions covering the following topics are welcome:

edaWorkshop15 Topics		
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<b>System Level and Hardware/Software Design of Embedded Systems</b> <ul style="list-style-type: none"><li>■ Specification- and Model-based Design</li><li>■ Architectural Synthesis and Optimization</li><li>■ Advanced Architectures (ASIPs, SoCs, MPSoCs, NoC, SiPs and Reconfigurable Architectures)</li><li>■ Transaction Level Modeling and Simulation</li><li>■ Development and Optimization of Hardware-dependent Software</li></ul> <b>Analog- and Mixed-Signal Design</b> <ul style="list-style-type: none"><li>■ Design Automation for Analog Circuits</li><li>■ Synthesis, Simulation and Verification</li><li>■ RF Circuits, Smart Power Circuits</li><li>■ Model Generation</li><li>■ Parasitics and Interconnects</li><li>■ Signal Integrity and EMC</li></ul>	<b>Design and Verification</b> <ul style="list-style-type: none"><li>■ Formal Verification</li><li>■ Statistical Timing Analysis and Variability</li><li>■ Low Power Design, Analysis and Optimization</li><li>■ Logic- and Technology-dependent Synthesis for Nanometer Circuits</li><li>■ Physical Design and Verification</li><li>■ Simulation Acceleration and Rapid Prototyping</li><li>■ Productivity and Efficiency of Design</li></ul> <ul style="list-style-type: none"><li>■ 3D Design, Packaging and SiP</li><li>■ Design for Integration of Multi-Domain components</li><li>■ Energy Efficient Design</li><li>■ Analysis and Optimization of Performance and Power</li><li>■ Cyber-Physical Systems</li><li>■ Design for New Technologies</li><li>■ Design for Specific Applications</li></ul> <b>More than Moore</b>	<b>Reliability, Robustness and Test</b> <ul style="list-style-type: none"><li>■ Design for Reliability and Robustness</li><li>■ Modeling of Aging Effects</li><li>■ Design Centering and Yield Optimization (DfM)</li><li>■ Fault-tolerant and Self-healing System Design</li><li>■ System Test and Production Test</li><li>■ Delay Test and Defect-oriented Test</li><li>■ BIST and Design for Testability</li><li>■ Test Generation, Diagnosis and Fault Modeling</li><li>■ Test of Regular Structures</li></ul>

## Committees of the edaWorkshop

Committees of the edaWorkshop		
<b>Program Committee</b> <ul style="list-style-type: none"><li>■ W. Anheier, U Bremen</li><li>■ M. Dietrich, Fraunhofer Institut für Integrierte Schaltungen</li><li>■ W. Ecker, Infineon Technologies AG</li><li>■ K. Hahn, U Siegen</li><li>■ A. Hoffmann, Synopsys GmbH</li><li>■ G. Kommann, Intel Mobile Communications</li><li>■ R. Pferdmeiges, Infineon Technologies AG</li><li>■ M. Schächtele, Robert Bosch GmbH</li><li>■ R. Sommer, IMMS gGmbH</li><li>■ P. van Staa, Robert Bosch GmbH</li></ul>	<b>Chair:</b> <ul style="list-style-type: none"><li>■ U. Schlichtmann, TU München</li><li>■ O. Bringmann, Forschungszentrum Informatik (FZI)</li></ul> <ul style="list-style-type: none"><li>■ R. Ernst, TU Braunschweig</li><li>■ P. Haspel, Cadence Design Systems GmbH</li><li>■ J. Kampe, FH Jena</li><li>■ S. Kern, Atmel Automotive GmbH</li><li>■ V. Meyer zu Bexten, Infineon Technologies AG</li><li>■ M. Reuter, Mentor Graphics GmbH</li><li>■ K. Schneider, TU Kaiserslautern</li><li>■ G. Teepe, GLOBALFOUNDRIES Dresden</li><li>■ N. Wehn, TU Kaiserslautern</li></ul>	<b>General Chairs of the edaWorkshop</b> <ul style="list-style-type: none"><li>■ W. Nebel, OFFIS - Institute for Information Technology, edacentrum</li><li>■ W. Rosenstiel, U Tübingen, edacentrum</li><li>■ W. Daehn, Fachhochschule Magdeburg-Stendal</li><li>■ R. Drechsler, U Bremen</li><li>■ V. Glauert, U Erlangen-Nürnberg</li><li>■ L. Hedrich, U Frankfurt</li><li>■ A. Herkersdorf, TU München</li><li>■ W. Kunz, TU Kaiserslautern</li><li>■ S. Sattler, U Erlangen-Nürnberg</li><li>■ H. Schmidt-Habich, Infineon Technologies AG</li><li>■ J. Teich, U Erlangen-Nürnberg</li><li>■ H.-J. Wunderlich, U Stuttgart</li></ul> <b>Organization Committee</b> <ul style="list-style-type: none"><li>■ J. Haase, edacentrum</li><li>■ D. Treytnar, edacentrum</li><li>■ V. Schanz, ITG in VDE</li><li>■ R. Popp, edacentrum</li><li>■ P. Federer, GI</li><li>■ R. Schnabel, VDE/VDI-GMM</li></ul>

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**Quell-URL:** <https://project.edacentrum.de/veranstaltungen/edaworkshop/2015/call>

### Links:

- [1] <https://project.edacentrum.de/system/files/files/edaworkshop/2015/edaWS15-call.pdf>
- [2] <https://project.edacentrum.de/edaworkshop/upload>
- [3] [https://project.edacentrum.de/system/files/files/edaworkshop/2015/edaworkshop\\_vorlage\\_tex.zip](https://project.edacentrum.de/system/files/files/edaworkshop/2015/edaworkshop_vorlage_tex.zip)
- [4] [https://project.edacentrum.de/system/files/files/edaworkshop/2015/edaworkshop\\_vorlage\\_word.zip](https://project.edacentrum.de/system/files/files/edaworkshop/2015/edaworkshop_vorlage_word.zip)